



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

技术要求:

- 1) 材质:见附表;
- 2) 电镀:见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm~1.6mm

温度范围: -25℃~85℃

额定电压: 250V AC/DC

额定电流: 3A

接触电阻: < 0.01Ω

绝缘电阻: > 1000MΩ

耐 压: 1000V AC/minute

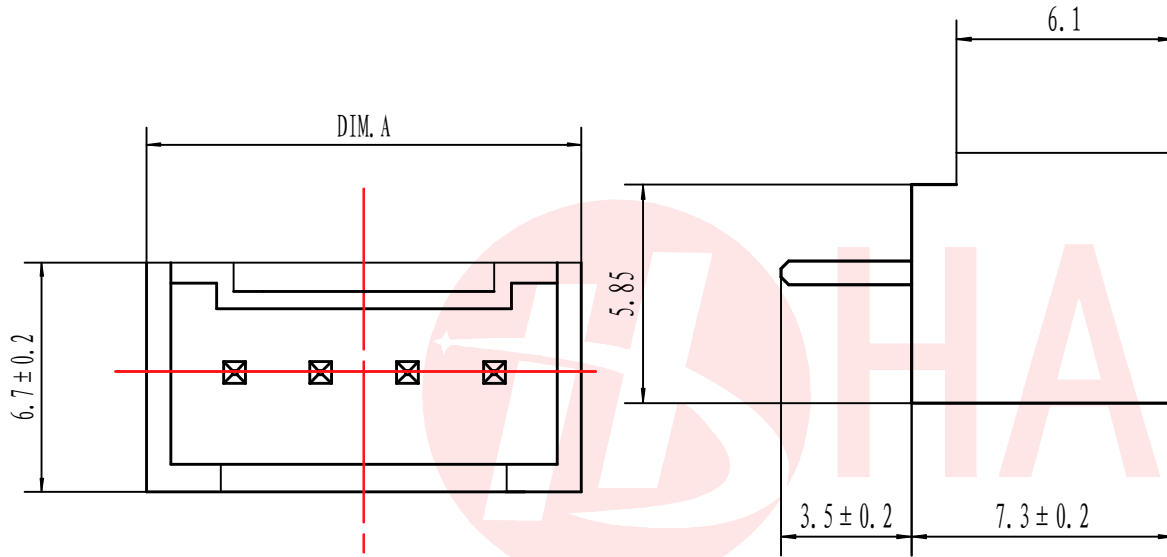
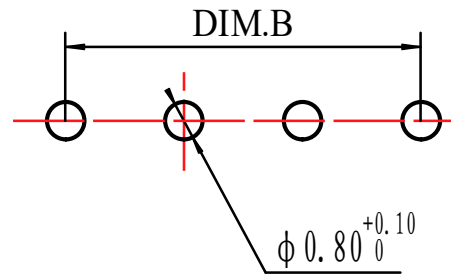
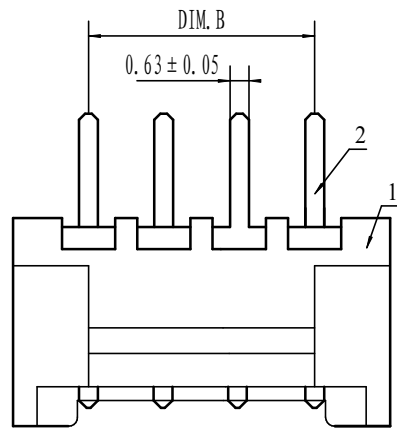


TABLE:

CSG PART NO.	Dimension mm		
	PIN#	DIM A	DIM B
WAFER-XHB254Z-2AH	2P	7.50	2.50
WAFER-XHB254Z-3AH	3P	10.00	5.00
WAFER-XHB254Z-4AH	4P	12.50	7.50
WAFER-XHB254Z-5AH	5P	15.00	10.00
WAFER-XHB254Z-6AH	6P	17.50	12.50
WAFER-XHB254Z-7AH	7P	20.00	15.00
WAFER-XHB254Z-8AH	8P	22.50	17.50
WAFER-XHB254Z-9AH	9P	25.00	20.00
WAFER-XHB254Z-10AH	10P	27.50	22.50
WAFER-XHB254Z-11AH	11P	30.00	25.00
WAFER-XHB254Z-12AH	12P	32.50	27.50
WAFER-XHB254Z-15AH	15P	40.00	35.00



PCB LAYOUT

NO.	NAME	Q' TY	DESCRIPTION
2	PIN	n PCS	材质:黄铜,电镀:镀亮锡60u"MIN
1	Housing	1 PCS	材质:PA66 (UL94V-0),颜色:本色

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.35	X :±2°
X.X :±0.25	X.X :±1°
X.XX :±0.15	



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER XHS 2.54立式DIP直针红色			
DWN	xiong	PART NO.WAFER-XHB254Z-NAH		
CHKD	lee	SCALE:1:1	UNIT: mm	☉
APVD	wang	SIZE: A4	SHEET:10F 1	REV: A4

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